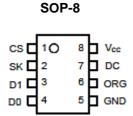


General Description

The EC93C56A/66A provides 2048/4096 bits of serial electrically erasable programmable read only memory (EEPROM) organized as 128/256 words of 16 bits each, when the ORG pin is connected to VCC and 256/512 words of 8 bits each when it is tied to ground. The EC93C56A/66A is available in space-saving PDIP-8, SOP-8, TSSOP-8, MSOP-8, and DFN-8 packages. The EC93C56A/66A is enabled through the Chip Select pin (CS), and accessed via a 3-wire serial interface consisting of Data Input (DI), Data Output (DO), and Shift Clock (SK). Upon receiving a Read instruction at DI, the address is decoded and the data is clocked out serially on the data output pin DO. The WRITE cycle is completely self-timed and no separate erase cycle is required before write. The Write cycle is only enabled when it is in the Erase/Write Enable state. When CS is brought "high" following the initiation of a write cycle, the DO pin outputs the Ready/Busy status.

Pin Configuration

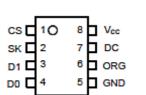


Top view

Pin Name	Functions	
CS	Chip Select	
SK	Serial Data Clock	
DI	Serial Data Input	
DO	Serial Data Output	
GND	Ground	
Vcc	Power Supply	
ORG	Internal Organization	
DC	Don't Connect	

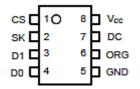
Features

- Low-voltage Operation
 - 1.7V (VCC = 1.7V to 5.5V)
- **Three-wire Serial Interface**
- Sequential Read Operation
- 2 MHz Clock Rate (5V) Compatibility •
- Self-timed Write Cycle (5 ms max)
- High-reliability
 - Endurance: 1 Million Write Cycles
 - Data Retention: 100 Years
- PDIP-8, SOP-8, TSSOP-8, MSOP-8 and DFN-8 packages.



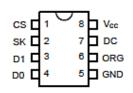
TSSOP-8

MSOP-8



Top view

PDIP-8



Top view



Top view

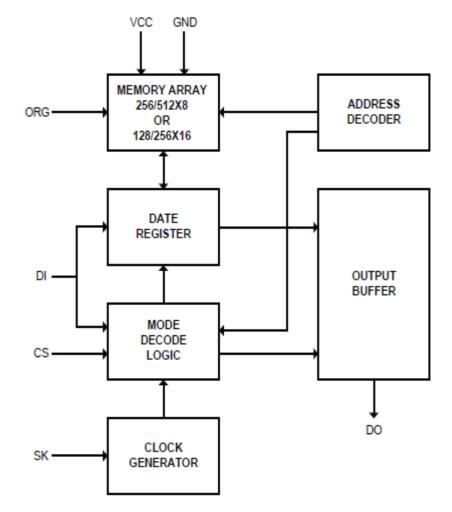
DFN-8

Vcc	8	1	cs
DC	7	2	SK
ORG	6	3	D1
GND	5	4	D0

Bottom view



Block Diagram



Notes: When the ORG pin is connected to VCC, the "x 16" organization is selected. When it is connected to ground, the "x 8" organization is selected. If the ORG pin is left unconnected and the application does not load the input beyond the capability of the internal 1 Meg ohm pullup, then the "x 16" organization is selected.



Function Descriptions

The EC93C56A/66A is accessed via a simple and versatile three-wire serial communication interface. Device operation is controlled by seven instructions issued by the host processor. A valid instruction starts with a rising edge of CS and consists of a start bit (logic"1") followed by the appropriate op code and the desired memory address location.

Instruction	S D	OP Code	Addr	ess	Da	ata	Comments
Instruction	5	OF Code	x8	x16	x8	x16	Comments
READ	1	10	A8 - A0	A7 - A0			Reads data stored in memory, at specified address
EWEN	1	00	11XXXXXXX	11XXXXXX			Write enable must precede all programming modes
ERASE	1	11	A8 - A0	A7 - A0			Erase memory location An - A0
WRITE	1	01	A8 - A0	A7 - A0	D7 - D0	D15 - D0	Writes memory location An - A0
ERAL	1	00	10XXXXXXX	10XXXXXX			Erases all memory locations. Valid only at VCC=4.5V to 5.5V
WRAL	1	00	01XXXXXXX	01XXXXXX	D7 - D0	D15 - D0	Writes all memory locations. Valid only at VCC=4.5V to 5.5V
EWDS	1	00	00XXXXXXX	00XXXXXX			Disables all programming instructions

Instruction set for the EC93C56A/66A

Notes: The X's in the address field represent don't care values and must be clocked.

READ (READ): The Read (READ) instruction contains the address code for the memory location to be read. After the instruction and address are decoded, data from the selected memory location is available at the serial output pin DO. Output data changes are synchronized with the rising edges of serial clock SK. It should be noted that a dummy bit (logic "0") precedes the 8- or 16-bit data output string. The EC93C56A/66A supports sequential read operations. The device will automatically increment the internal address pointer and clock out the next memory location as long as Chip Select (CS) is held high .In this case, the dummy bit (logic "0") will not be clocked out between memory locations, thus allowing for a continuous steam of data to be read.

ERASE/WRITE (EWEN): To assure data integrity, the part automatically goes into the Erase/Write Disable (EWDS) state when power is first applied. An Erase/Write Enable (EWEN) instruction must be executed first before any programming instructions can be carried out. Please note that once in the EWEN state, programming remains enabled until an EWDS instruction is executed or VCC power is removed from the part.

ERASE (ERASE): The Erase (ERASE) instruction programs all bits in the specified memory location to the logical "1" state. The self-timed erase cycle starts once the ERASE instruction and address are decoded. The DO pin outputs the Ready/Busy status of the part if CS is brought high after being kept low for a minimum of 250 ns (TCS). A logic "1" at pin DO indicates that the selected memory location has been erased, and the part is ready for another instruction.

WRITE (WRITE): The Write (WRITE) instruction contains the 8 or 16 bits of data to be written into the specified memory location. The self-timed programming cycle, tWP, starts after the last bit of data is received at serial data input pin DI. The DO pin outputs the Ready/Busy status of the part if CS is brought high after being kept low for a minimum of 250 ns (TCS). A logic "0" at DO indicates that programming is still in progress. A logic "1" indicates that the memory location at the specified address has been written with the data pattern contained in the instruction and the part is ready for further instructions. A Ready/Busy status cannot be obtained if the CS is brought high after the end of the selftimed programming cycle, TWP.

ERASE ALL (ERAL): The Erase All (ERAL) instruction programs every bit in the memory array to the logic "1" state and is primarily used for testing purposes. The DO pin outputs the Ready/Busy status of the part if CS is brought high after being kept low for a minimum of 250 ns (TCS). The ERAL instruction is valid only at VCC = $5.0V \pm 10\%$.

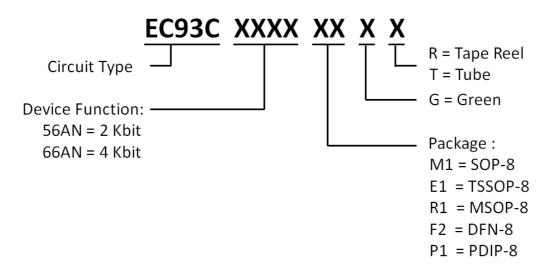


Function Descriptions

WRITE ALL (WRAL): The Write All (WRAL) instruction programs all memory locations with the data patterns specified in the instruction. The DO pin outputs the Ready/Busy status of the part if CS is brought high after being kept low for a minimum of 250 ns (TCS). The WRAL instruction is valid only at VCC = $5.0V \pm 10\%$.

ERASE/WRITE DISABLE (EWDS): To protect against accidental data disturb, the Erase/Write Disable (EWDS) instruction disables all programming modes and should be executed after all programming operations. The operation of the Read instruction is independent of both the EWEN and EWDS instructions and can be executed at any time.

Ordering Information



Marking Information

Package Type	Part Number	Marking	Marking Information
SOP-8	EC93CXXANM1GX		
TSSOP-8	EC93CXXANE1GX	93CXXA LLLLL	LLLLL is the last five numbers of wafer lot number YYWW is Date Code.
MSOP-8	EC93CXXANR1GX	YYWWT	T is tracking Code ,T=X
PDIP-8	EC93CXXANP1GX		
DFN-8	EC93CXXANF2GX	CXXA LLLL	XX is the memory of production. LLLL is the last four numbers of wafer lot number

Available Package Types

Part Number	SOP-8	TSSOP-8	MSOP-8	DFN-8	PDIP-8
EC93C56A	V	V	V	V	V
EC93C66A	V	V	V	V	V



Electrical Characteristics

Comments

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to this device. These are stress ratings only. Functional operation of this device at these or any other conditions above those indicated in the operational sections of this specification is not implied or intended. Exposure to the absolute maximum rating conditions for extended periods may affect device reliability.

DC Characteristics

Applicable over recommended operating range from: $T_A = -40^{\circ}$ to $+85^{\circ}$, V cc = +1.7V to +5.5V (unless otherwise noted)

Symbol	Parameter	Test Co	ondition	Min	Тур	Max	Units
Vcc1	Supply Voltage	-		1.8	-	5.5	V
Vcc2	Supply Voltage	-		2.7	-	5.5	V
Vcc3	Supply Voltage	-		4.5	-	5.5	V
lcc	Supply Current	Vcc=5.0V	Read at 1.0 MHz	-	0.5	2.0	mA
	Supply Sullen	VCC-0.0V	Write at 1.0 MHz	-	2	3.0	mA
SB1	Standby Current	Vcc=1.7V	CS=0V	-	-	1.0	μA
SB2	Standby Current	Vcc=2.7V	CS=0V	-	-	1.0	μA
SB3	Standby Current	Vcc=5.0V	CS=0V	-	-	1.0	μA
IIL(1)	Input Leakage	VIN=0V	to Vcc	-	0.1	1.0	μA
IL(2)	Input Leakage	VIN=0V	to Vcc	-	2.0	3.0	μA
lol	Output Leakage	VIN=0V	to Vcc	-	0.1	1.0	μA
VIL1(3)	Input Low Voltage	2.7V ≤ V		-0.3	-	0.8	V
VIH1(3)	Input High Voltage	$2.7 \vee \leq \vee 0$	$00 \leq 0.5 \text{ V}$	2.0	-	Vcc+0.3	V
VIL2(3)	Input Low Voltage	1.01/~1/		-0.5	-	Vccx0.3	V
VIH2(3)	Input High Voltage	1.8V ≤ Vo	$CC \leq Z.7 V$	Vccx0.7	-	Vcc+0.3	V
VIL3(3)	Input Low Voltage	Mar	1 7)/	-0.5	-	Vccx0.2	V
VIH3(3)	Input High Voltage	VCC=	Vcc= 1.7V		-	Vcc+0.3	V
Vol1	Output Low Voltage	27/(5)/(5 5 5)/ IOL=2.1mA		-	-	0.4	V
Vон1	Output High Voltage	$2.7V \le V_{CC} \le 5.5V$	IOH =-0.4mA	2.4	-	-	V
Vol2	Output Low Voltage	17/////////////////////////////////////	IOL=0.15mA	-	-	0.2	V
Vон2	Output High Voltage	1.7V ≤ Vcc ≤ 2.7V	IOH=-100µA	Vcc-0.2	-	-	V

Notes:

1. DI · CS · SK input pin

2. ORG input pin

3. VIL min and VIH max are reference only and are not tested.

Pin Capacitance

Applicable over recommended operating range from $T_A = 25$ °C, f = 1.0 MHz, V cc = +1.7V (unless otherwise noted)

Symbol	Test Conditions	Max	Unit	Conditions
COUT	Output Capacitance (DO)	5	pF	VOUT = 0V
CIN	Input Capacitance (CS, SK, DI, ORG)	5	pF	VIN = 0V



AC Characteristics

Applicable over recommended operating range from $T_A = -40$ °C to +85°C, V cc = +1.7V to +5.5V C_L = 1 TTL Gate and 100pF (unless otherwise noted)

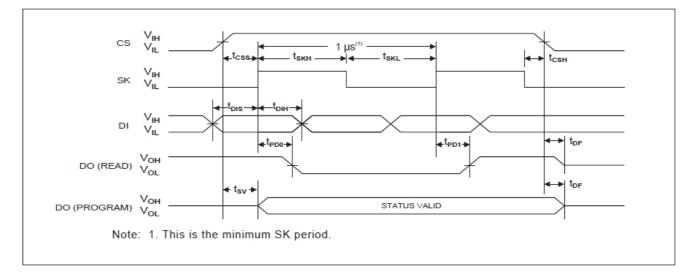
Symbol	Parameter	Test C	ondition	Min	Тур	Max	Units
		4.5V ≤ Y	Vcc≤5.5V	0		2	
fsк	SK Clock Frequency	2.7V ≤ `	Vcc≤5.5V	0	- 1	1	MHz
		1.7V ≤ '	Vcc≤5.5V	0		0.25	
		4.5V ≤ `	Vcc≤5.5V	250			
tsкн	SK High Time	2.7V ≤ '	Vcc≤5.5V	250	- 1	-	ns
	_	1.7V ≤ '	Vcc≤5.5V	1000			
		4.5V ≤ `	Vcc≤5.5V	250			
t skl	SK Low Time	2.7V ≤ `	Vcc≤5.5V	250] -	-	ns
		1.7V ≤ `	Vcc≤5.5V	1000			
		4.5V ≤ `	Vcc≤5.5V	250			
tcs	Minimum CS Low Time	2.7V ≤ `	Vcc≤5.5V	250	- 1	-	ns
		1.7V ≤ `	Vcc≤5.5V	1000			
			$4.5V \le V_{CC} \le 5.5V$	50			
tcss	CS Setup Time	Relative to SK	$2.7V \le V_{CC} \le 5.5V$	50] -	-	ns
			$1.7V \le Vcc \le 5.5V$	200			
			$4.5V \le V_{CC} \le 5.5V$	100			
tois	DI Setup Time	Relative to SK	$2.7V \le V_{CC} \le 5.5V$	100	-	-	ns
			$1.7V \le V_{CC} \le 5.5V$	400			
t csн	CS Hold Time	Relative to SK		0	-	-	ns
			$4.5V \le V_{CC} \le 5.5V$	100			
tын	DI Hold Time	Relative to SK	$2.7V \le V_{CC} \le 5.5V$	100	-	-	ns
			$1.7V \le V_{CC} \le 5.5V$	400			
			$4.5V \le V_{CC} \le 5.5V$	-		250	
tPD1	Output Delay to "1"	AC Test	$2.7V \le V_{CC} \le 5.5V$	-	-	250	ns
			$1.7V \le V_{CC} \le 5.5V$	-		1000	
			$4.5V \le V_{CC} \le 5.5V$	-		250	
tpd0	Output Delay to "0"	AC Test	$2.7V \le V_{CC} \le 5.5V$	-	- 1	250	ns
			$1.7V \le V_{CC} \le 5.5V$	-		1000	
			$4.5V \le V_{CC} \le 5.5V$	-	-	250	
tsv	CS to Status Valid	AC Test	$2.7V \le V_{CC} \le 5.5V$	-	- 1	250	ns
			$1.7V \le V_{CC} \le 5.5V$	-		1000	
	CS to DO in High	AC Test	$4.5V \le V_{CC} \le 5.5V$	-	1	100	
t df	Impedance	CS = VIL	$2.7V \le V_{CC} \le 5.5V$	-	-	100	ns
	-		$1.7V \le V_{CC} \le 5.5V$	-		400	
twp (1)	Write Cycle Time	-	-	-	1.5	5	ms
Endurance ⁽¹⁾	5.0V, 25℃		-	1M	-	-	Write Cycle

Note: 1. This parameter is characterized and is not 100% tested.



Timing Diagrams

Synchronous Data Timing



Organization Key for Timing Diagram

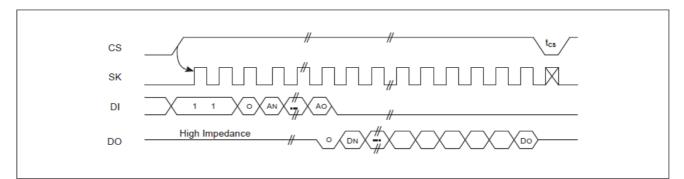
I/O	EC93C56A(2K)		EC93C	66A(4K)
1/0	X 8	X 16	X 8	X 16
AN	A8(1)	A7(2)	A8	A7
DN	D7	D15	D7	D15

Note : 1. A8 is a DON'T CARE value, but the extra clock is required. 2. A7 is a DON'T CARE value, but the extra clock is required.

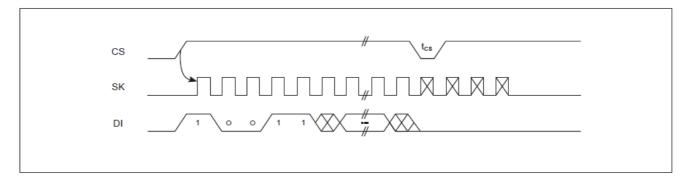




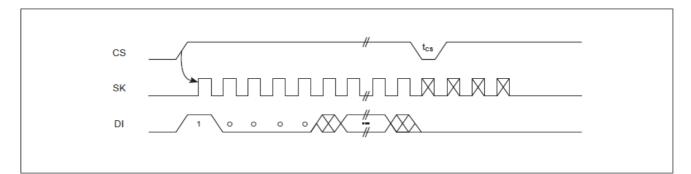
READ Timing



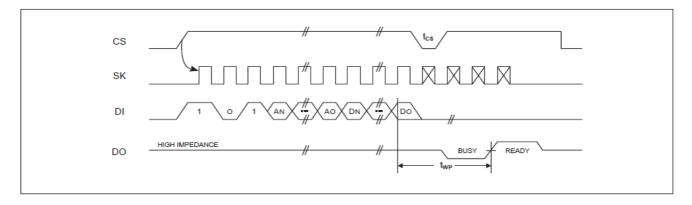
EWEN Timing



EWDS Timing



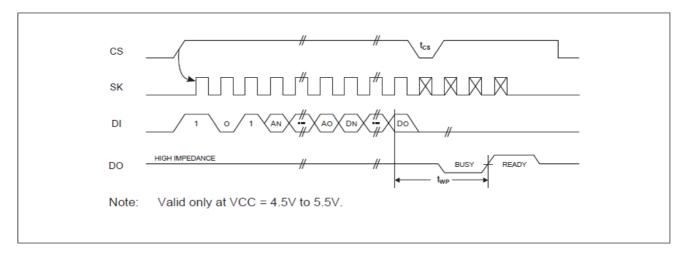
WRITE Timing



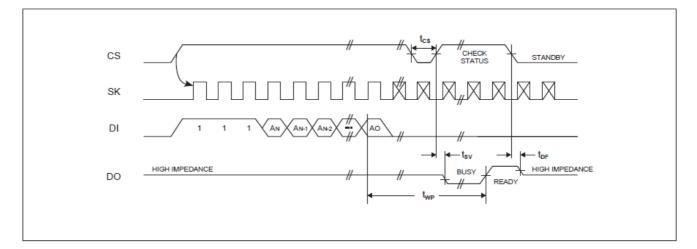




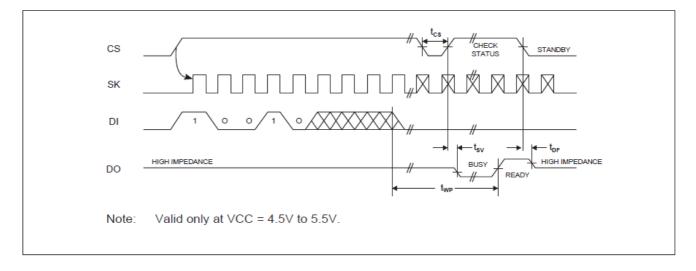
WRAL Timing



ERASE Timing



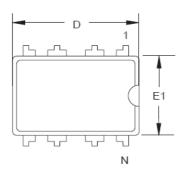




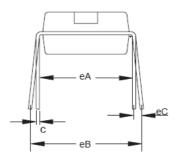


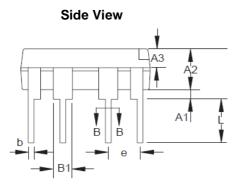
Mechanical Dimensions OUTLINE DRAWING PDIP - 8 Available package types : EC93C56A/66A

Top View

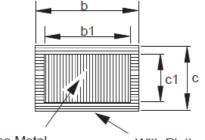


End View





Section B - B



Base Metal

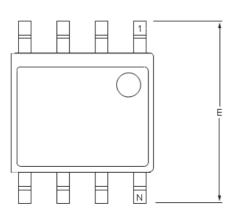
With Plating

SYMBOL	MIN	MAX		
A	3.60	4.00		
A1	0.51	-		
A2	3.10	3.50		
A3	1.50	1.70		
b	0.44	0.53		
b1	0.43	0.48		
В	1.52 BSC			
С	0.25	0.31		
c1	0.24	0.26		
D	9.05	9.45		
E1	6.15	6.55		
е	2.54	BSC		
eA	7.62 BSC			
eB	7.62	9.50		
eC	0	0.94		
L	3.00	-		

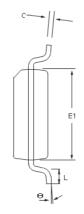


Mechanical Dimensions OUTLINE DRAWING SOP - 8 Available package types : EC93C56A/66A

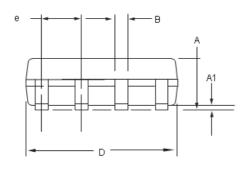
Top View



End View



Side View



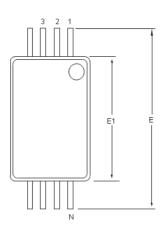
SYMBOL	MIN	MAX
А	1.35	1.75
A1	0.10	0.25
b	0.31	0.51
С	0.17	0.25
D	4.70	5.10
E1	3.80	4.00
E	5.79	6.20
e	1.27	BSC
L	0.40	1.27
θ	0°	8°



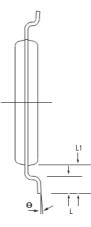


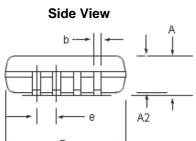
Mechanical Dimensions OUTLINE DRAWING TSSOP - 8 Available package types : EC93C56A/66A











SYMBOL	MIN	MAX	
D	2.80	3.20	
E	6.20	6.60	
E1	4.20	4.60	
А	-	1.20	
A2	0.80	1.15	
b	0.19	0.30	
е	0.65	BSC	
L	0.45	0.75	
L1	1.00 BSC		
θ	0°	8°	

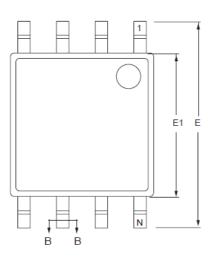


EC93C56A/66A

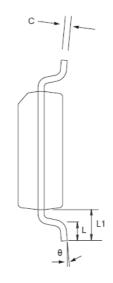
Three-wire Serial EEPROM

Mechanical Dimensions OUTLINE DRAWING MSOP - 8 Available package types : EC93C56A/66A

Top View



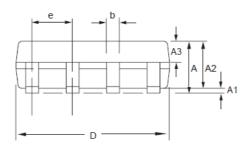
End View



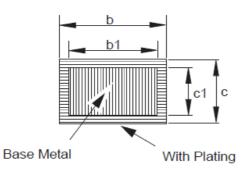
COMMON DIMENSIONS (Unit of Measure = mm)

SYMBOL	MIN	MAX
A	-	1.10
A1	0.05	0.15
A2	0.75	0.95
A3	0.30	0.40
b	0.29	0.38
b1	0.28	0.33
С	0.15	0.20
c1	0.14	0.16
D	2.90	3.10
E	4.70	5.10
E1	2.90	3.10
е	0.65 BSC	
L	0.40	0.70
L1	0.95 BSC	
θ	0°	8°

Side View

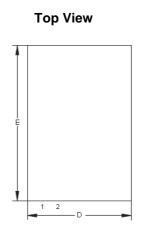


Section B -B





Mechanical Dimensions OUTLINE DRAWING DFN - 8 Available package types : EC93C56A/66A

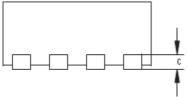


Side View





Bottom View



SYMBOL	MIN	MAX
А	0.70	0.80
A1	-	0.05
b	0.18	0.30
С	0.18	0.25
D	1.90	2.10
D2	1.50 REF	
е	0.50 BSC	
Nd	1.50 BSC	
E	2.90	3.10
E2	1.60 BSC	
L	0.30	0.50
h	0.20	0.30

